





#### 100V PNP LED DRIVING TRANSISTOR IN SOT89

#### **Features**

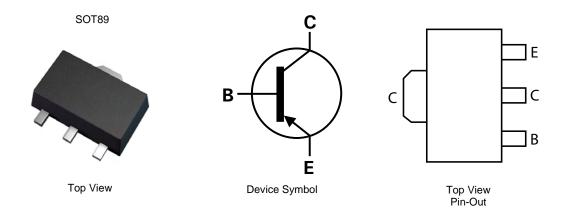
- BV<sub>CEO</sub> > -100V
- Maximum continuous current I<sub>C</sub> = -1A
- $h_{FE} > 100 @ I_C = -150 mA, V_{CE} = -0.2 V$
- Lead Free, RoHS Compliant (Note 1)
- Halogen and Antimony Free "Green" Device (Note 2)
- · Qualified to AEC-Q101 Standards for High Reliability

## Applications

LED TV backlight

#### **Mechanical Data**

- Case: SOT89
- Case material: molded Plastic. "Green" molding Compound.
- UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish
- Weight: 0.052 grams (Approximate)



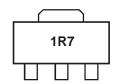
## Ordering Information (Note 3)

Product	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
ZXTP4003ZTA	1R7	7	12	1000 units

Notes:

- 1. No purposefully added lead.
- 2. "Green" devices, Halogen and Antimony Free, Diodes Inc's "Green" Policy can be found on our website at http://www.diodes.com
- 3. For Packaging Details, go to our website at http://www.diodes.com.

### **Marking Information**



1R7 = Product type Marking Code

ZXTP4003Z
Datasheet Number: DS35460 Rev. 1 - 2
Downloaded From Oneyac.com



### Maximum Ratings @TA = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V <sub>CBO</sub>	-100	V
Collector-Emitter Voltage	V <sub>CEO</sub>	-100	V
Emitter-Base Voltage	V <sub>EBO</sub>	-7	V
Continuous Collector Current	Ic	-1	А
Peak Pulse Current (Note 4)	I <sub>CM</sub>	-3	Α
Base Current	I <sub>B</sub>	-500	mA

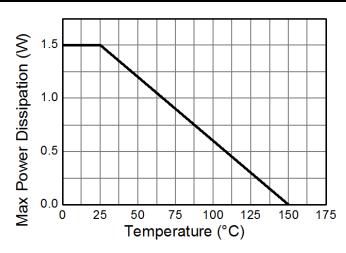
## Thermal Characteristics @TA = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	P <sub>D</sub>	1.5	W
Thermal Resistance, Junction to Ambient (Note 5)	$R_{\theta JA}$	83	°C/W
Thermal Resistance, Junction to Leads (Note 6)	$R_{ heta JL}$	17.46	°C/W
Operating and Storage Temperature Range	T <sub>J.</sub> T <sub>STG</sub>	-55 to +150	°C

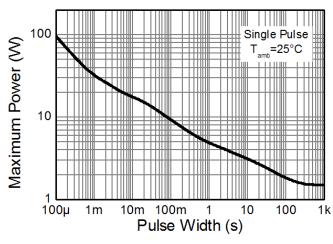
Notes:

- 4. Measured under pulsed conditions. Pulse width = 300µs. Duty cycle ≤ 2%.
- 5. For a device surface mounted on 25mm X 25mm FR4 PCB with high coverage of single sided 1 oz copper, in still air conditions
- 6. Thermal resistance from junction to solder-point (on the exposed collector pad).

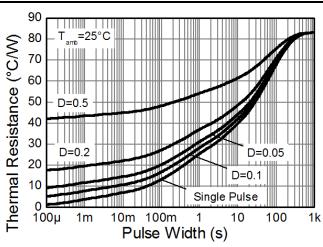
### Thermal Characteristics and Derating Information



# **Derating Curve**



# **Pulse Power Dissipation**



# **Transient Thermal Impedance**

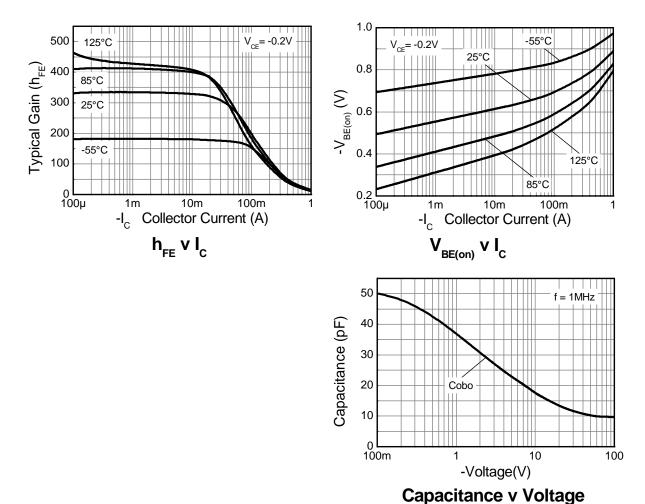


## Electrical Characteristics @TA = 25°C unless otherwise specified

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Collector-Emitter Breakdown Voltage (Note 7)	BV <sub>CEO</sub>	-100	-170	-	V	$I_C = -10 \text{mA}$
Collector Cut-off Current	I <sub>CBO</sub>	-	-	-50	nA	V <sub>CB</sub> = -100V
Emitter Cut-off Current	I <sub>EBO</sub>	-	-	-50	nA	$V_{EB} = -7V$
Static Forward Current Transfer Ratio (Note 7)	h <sub>FE</sub>	60 100	133 112	-	-	$I_C = -85 \text{mA}, V_{CE} = -0.15 \text{V}$ $I_C = -150 \text{mA}, V_{CE} = -0.2 \text{V}$
Base-Emitter Turn-On Voltage (Note 7)	V <sub>BE(on)</sub>	-	-0.71	-0.95	V	$I_C = -150 \text{mA}, V_{CE} = -0.2 \text{V}$
Delay Time	t <sub>(d)</sub>	-	378	-	ns	
Rise Time	t <sub>(r)</sub>	-	388	-	ns	$V_{CC} = -80V, I_{C} = -150mA,f$
Storage Time	t <sub>(s)</sub>	-	1348	-	ns	$-I_{B2} = 1.5 \text{mA}, V_{CE(ON)} = -0.2 \text{V}$
Fall Time	t <sub>(f)</sub>	-	382	-	ns	
Storage Time	t <sub>(s)</sub>	-	75	-	ns	$V_{CC} = -80V, I_{C} = -150mA,$
Fall Time	t <sub>(f)</sub>	-	363	-	ns	$-I_{B2} = -1.5$ mA, $V_{CE(ON)} = -4$ V

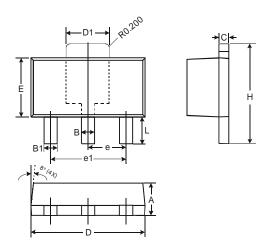
Notes: 7. Measured under pulsed conditions. Pulse width =  $300\mu s$ . Duty cycle  $\leq 2\%$ 

# Electrical Characteristics @T<sub>A</sub> = 25°C unless otherwise specified



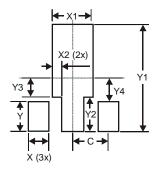


# **Package Outline Dimensions**



SOT89				
Dim	Min	Max		
Α	1.40	1.60		
В	0.44	0.62		
B1	0.35	0.54		
С	0.35 0.43			
D	4.40	4.60		
D1	1.52	1.83		
Е	2.29	2.60		
е	1.50 Typ			
e1	3.00 Typ			
Н	3.94	4.25		
L	0.89	1.20		
All Dimensions in mm				

# **Suggested Pad Layout**



Dimensions	Value (in mm)			
Х	0.900			
X1	1.733			
X2	0.416			
Υ	1.300			
Y1	4.600			
Y2	1.475			
Y3	0.950			
Y4	1.125			
С	1.500			





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